IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Alcoe et al.

Serial No.:

Dkt. No.: END920010135US2

Filed:

Examiner:

Title: THERMALLY ENHANCED LID FOR MULTICHIP MODULES

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Preliminary Amendment

Sir:

Kindly enter this amendment prior to initial examination

In the Specification:

Page 1, between lines 1 and 2, insert: --This application is a divisional of Serial No. 10/198,393; filed on 7/16/2002.--